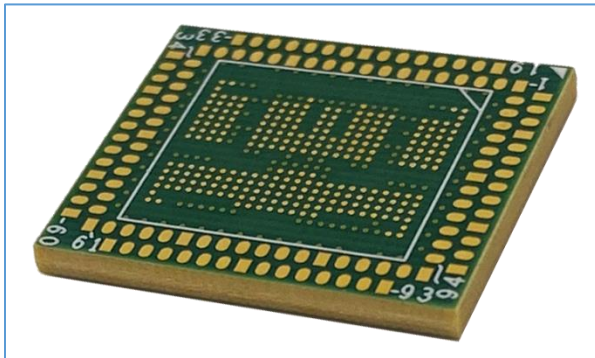


LPDDR4 & LPDDR4x Interposers

LPDDR4/4x 254 Ball XH Series Direct Attach Interposer



Key Features

- LPDDR4/4x
- XH Series Universal Probe Interposer
- 254-Ball
- 2 Channel x16 Memory Component
- High Fidelity
- Enables Oscilloscope Probing

Applications

- LPDDR4/4x
 - Memory validation and debug
 - Monitoring bus traffic
 - Bus traffic measurement
 - Analog insight

Simulation and De-Embedding

S-Parameters are included for target simulation and the creation of de-embedding filters for use with an oscilloscope.

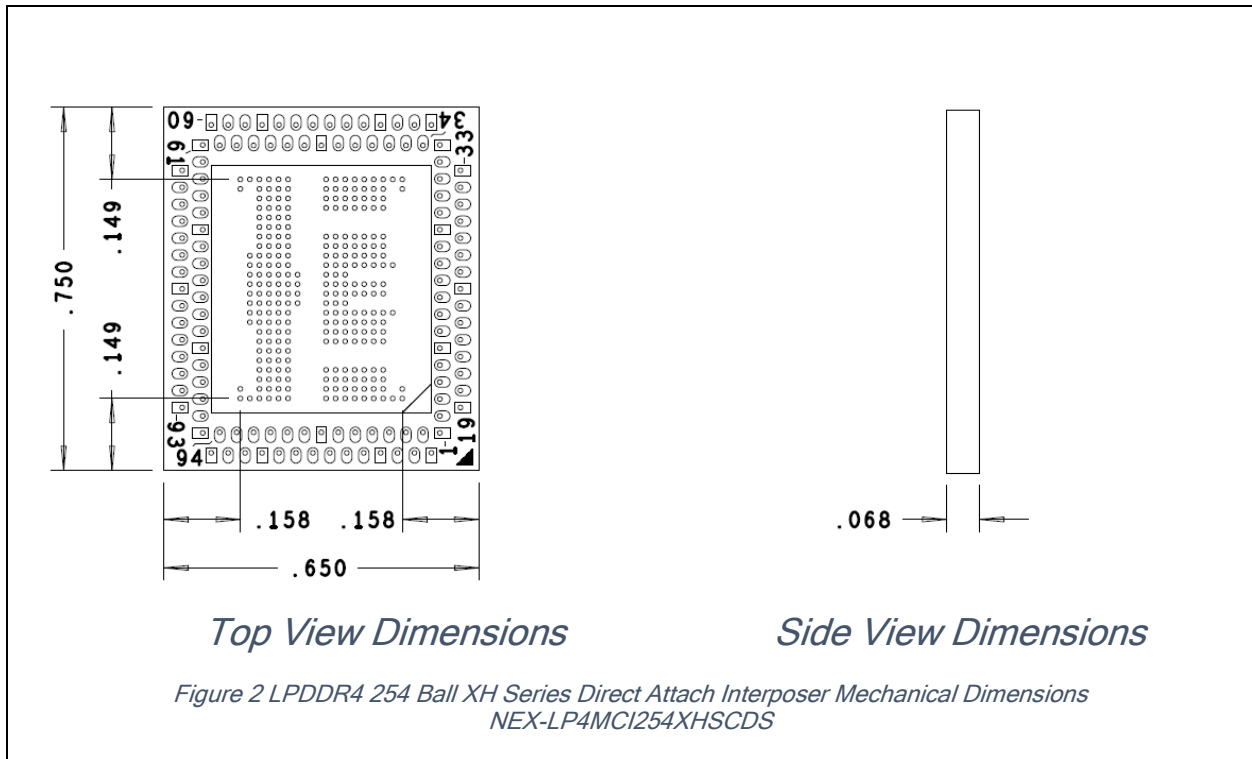
Attachment Service

Nexus Technology's expert attachment service provides a ready-to-go test solution customized to your application. We will attach the interposer and any additional accessories to your application's target. We can also power-on and test your application to confirm functionality. Please contact us for more information.

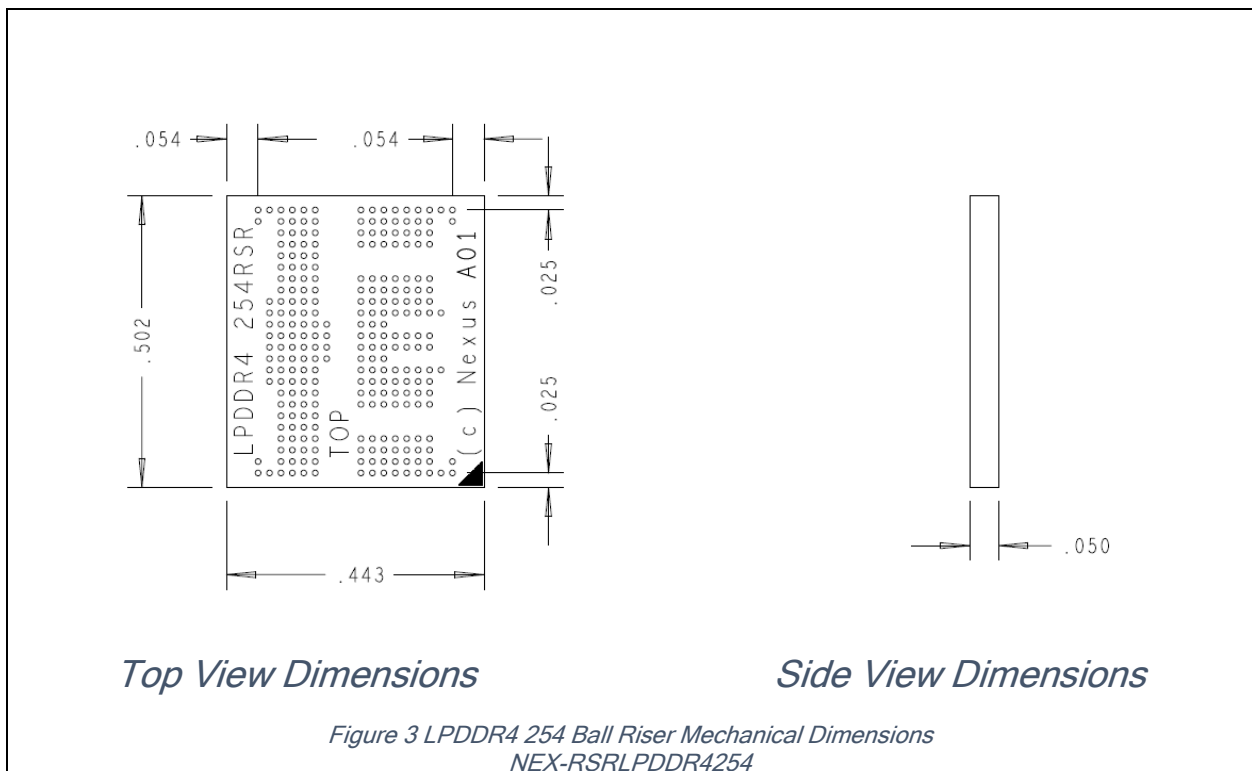


Figure 1 Direct Attach interposer installed under a memory component

Mechanical Outline



Note: All measurements listed are in inches



Note: All measurements listed are in inches

Probe Point Signal List

TEST Point	Signal	TEST Point	Signal	TEST Point	Signal	TEST Point	Signal	TEST Point	Signal
1	GROUND	25	VSF9	49	DMI0_B	73	GROUND	97	ODTca_A
2	DQ14_A	26	GROUND	50	GROUND	74	DAT7	98	DQS1_t_A
3	DQ12_A	27	CMD	51	DQ6_B	75	CKE2_A	99	DQS1_c_A
4	DQ13_A	28	DQ8_B	52	DQ4_B	76	CS1_A	100	GROUND
5	VSF7	29	DQ10_B	53	DQ7_B	77	CS0_A	101	DQS0_t_A
6	GROUND	30	DQ11_B	54	DQ15_B	78	GROUND	102	DQS0_c_A
7	VSF5	31	DMI1_B	55	CKE2_B	79	GROUND	103	DQ5_A
8	VSF3	32	DQ9_B	56	CA0_B	80	CKE0_B	104	DQ0_A
9	VSF1	33	GROUND	57	GROUND	81	CKE1_B	105	DQ1_A
10	VSF2	34	DQ2_B	58	CA4_B	82	CLK_c_B	106	DQ2_A
11	VSF4	35	DQ1_B	59	CA2_B	83	CLK_t_B	107	GROUND
12	VSF6	36	DQ0_B	60	GROUND	84	CLK	108	CA2_A
13	GROUND	37	DQ5_B	61	GROUND	85	DAT3	109	CA4_A
14	VSF8	38	DQS0_c_B	62	RESET_n	86	GROUND	110	GROUND
15	DQ13_B	39	DQS0_t_B	63	CS0_B	87	DAT1	111	CA0_A
16	DQ12_B	40	GROUND	64	CS1_B	88	DS	112	CS2_A
17	DQ14_B	41	DQS1_c_B	65	CS2_B	89	CLK_t_A	113	DQ15_A
18	GROUND	42	DQS1_t_B	66	GROUND	90	CLK_c_A	114	DQ7_A
19	GROUND	43	ODTca_B	67	RST_n	91	CKE1_A	115	DQ4_A
20	DQ9_A	44	CA1_B	68	DAT2	92	CKE0_A	116	DQ6_A
21	DMI1_A	45	CA3_B	69	DAT0	93	GROUND	117	GROUND
22	DQ11_A	46	CA5_B	70	DAT5	94	CA5_A	118	DMI0_A
23	DQ10_A	47	GROUND	71	DAT4	95	CA3_A	119	DQ3_A
24	DQ8_A	48	DQ3_B	72	DAT6	96	CA1_A	120	GROUND

Probe Point Locations

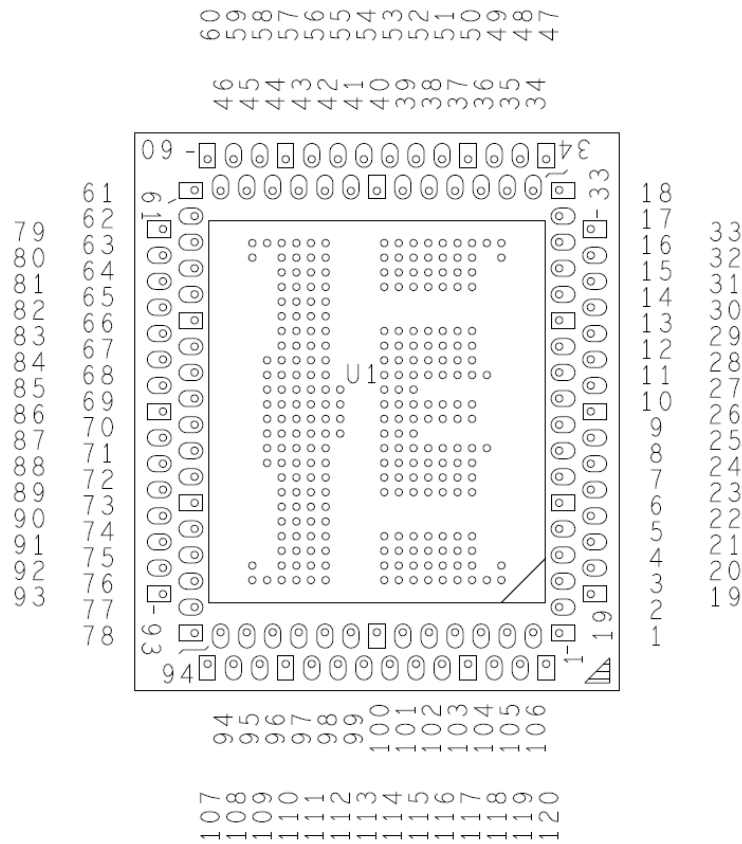


Figure 4 LPDDR4 254 Ball XH Series Direct Attach Interposer Probe Point Locations

Product Configuration Table

Nomenclature	Solder Balls on Interposer	Riser Included
NEX-LP4MCI254XHSCDS	Yes	No

Available Accessories

Type	Desc.	Quantity	Nomenclature
Riser	LPDDR4 254-Ball Riser elevates interposer 0.050"	1	NEX-RSRLPDDR4254 ¹
Memory Socket	LPDDR4 254-Ball BGA Memory Socket	1	NEX-SOCKETLPDDR4254 ²

¹ P/N NEX-RSRLPDDR4254 includes solderballs.

² P/N NEX-SOCKETLPDDR4254 does not include solderballs.

Attachment Service Options

Attachment Service Level	Description
Attachment Service	Contact us for more information

Contact Information

For more information, please contact us by telephone, email or mail as listed below. Normal business hours are 9:00 - 5:00 EDT/EST.

Web	www.nexustechnology.com
Telephone	877.595.8116
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Fax	877.595.8118
Address	78 Northeastern Blvd. Unit 2 Nashua, NH 03062
Email	support@nexustechnology.com